

S/N 10/823,314

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Neo C. Peng et al.

Examiner: Samuel M Heinrich

Serial No.: 10/823,314

Group Art Unit: 1725

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Docket No.: 303.772US2

Title: WAFER DICING DEVICE AND METHOD

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on February 11, 2008. Please amend the above-identified patent application as follows.